


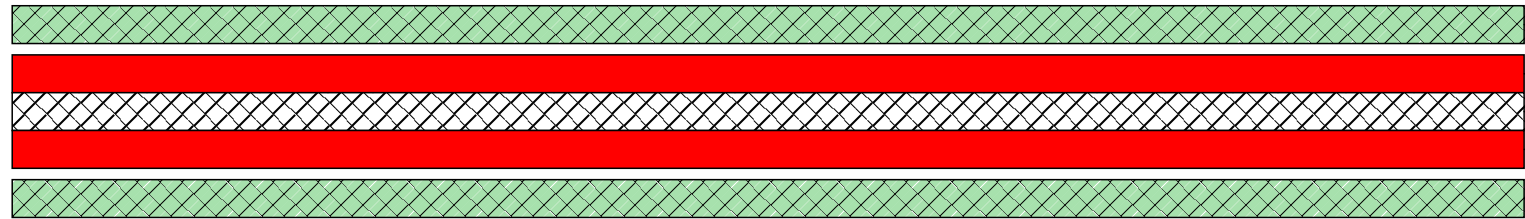
# Rigid

# Layer	Thickness	Description	Dk	Df	Note
Top Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts
1 Top Side	0.030mm	Starting foil 1/4oz. after plating and processing			
	0.050mm	Flexible core IPC-4204/11	3,4	0,002	Flex Polyimide adhesiveless
2 Inner Layer 1	0.017mm	ED Base Copper			
	0.100mm	Prepreg IPC-4101/127/128	4,4	0,011	LowFlow FR-4.1 filled, halogen free
	0.510mm	Core IPC-4101/127/128	5,1	0,011	FR-4.1 filled, halogen free
	0.065mm	Prepreg IPC-4101/127/128	3,5	0,011	FR-4.1 filled, halogen free
3 Bottom Side	0.030mm	Starting foil 1/4oz. after plating and processing			
Bottom Solder	0.015mm	Soldermask IPC-SM840	3,5	0,028	used on rigid parts

**Total thickness: 0.832mm**

notes:	<b>FLEX3_2F-1Ri_0,83_17_V2.12</b>			
Final copper thickness according to IPC-6013	PCB Thickness Tolerance: rigid ± 10% / flex ± 0,05mm			
IPC 2223 use A "Flex to install"	customer		created	
	pcb name		approved	
Please regard to our sectional design rules: ▶ <a href="http://www.we-online.com">www.we-online.com</a>	engineer		format A4, landscape	
	date			
Template Revision: 02/2021 by Andreas Schilpp / Michael Kress / Werner Öchslen				

# Flex



#	Layer	Thickness	Description	Dk	Df	Note
	flexible Soldermask Top	0.040mm	Soldermask JIS-C-5012/IPC-SM840	4,3	0,05	flexibel, thermal cured
1	Top Side	0.030mm	Starting foil 1/4oz. after plating and processing			
		0.050mm	Flexible core IPC-4204/11	3,4	0,002	Flex Polyimide adhesiveless
2	Inner Layer 1	0.017mm	ED Base Copper			
	Coverlay Bottom	0.040mm	PI Coverlay IPC-4203/2	3,6	0,02	Polyimide + bonding film (Epoxy)
<b>Total thickness: 0.177mm</b>						

notes:	<b>FLEX3_2F-1Ri_0,83_17_V2.12</b>		
Final copper thickness according to IPC-6013	PCB Thickness Tolerance: rigid $\pm 10\%$ / flex $\pm 0,05\text{mm}$		
IPC 2223 use A "Flex to install"	customer		created
	pcb name		approved
Please regard to our sectional design rules: ▶ <a href="http://www.we-online.com">www.we-online.com</a>	engineer		format A4, landscape
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